

## CEFM101-G Thru. CEFM105-G

Reverse Voltage: 50 to 600 Volts

Forward Current: 1.0 Amp

RoHS Device

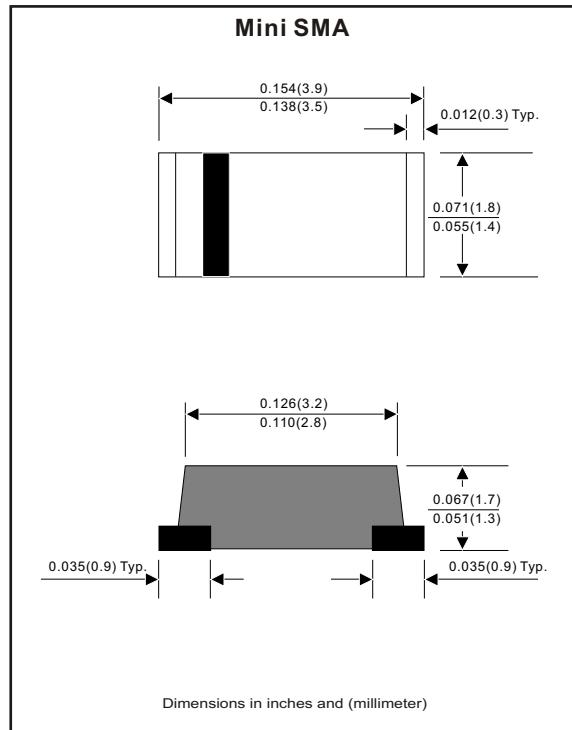


### Features

- Ideal for surface mount applications.
- Easy pick and place.
- Plastic package has Underwriters Lab. flammability classification 94V-0.
- Super fast recovery time for high efficient.
- Built-in strain relief.
- Low forward voltage drop.

### Mechanical data

- Case: Molded plastic, JEDEC SOD-123/Mini SMA.
- Terminals: Solderable per MIL-STD-750, method 2026.
- Polarity: Indicated by cathode band.
- Weight: 0.04 grams approx.



### Maximum Ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	CEFM 101-G	CEFM 102-G	CEFM 103-G	CEFM 104-G	CEFM 105-G	Unit
Max. repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	V
Max. DC blocking voltage	$V_{DC}$	50	100	200	400	600	V
Max. RMS voltage	$V_{RMS}$	35	70	140	280	420	V
Max. averaged forward current	$I_o$			1.0			A
Maximum Instantaneous forward voltage at $I_F=1.0\text{A}$	$V_F$		0.875		1.10	1.25	V
Forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	$I_{FSM}$			30			A
Reverse recovery time	$T_{rr}$		25		35	50	nS
Reverse current at rated @ $T_A=25^\circ\text{C}$ DC blocking voltage @ $T_A=100^\circ\text{C}$	$I_R$			5.0 250			$\mu\text{A}$
Max. thermal resistance (Note 1)	$R_{\theta JL}$			42			$^\circ\text{C}/\text{W}$
Operating junction temperature	$T_J$		150				$^\circ\text{C}$
Storage temperature range	$T_{STG}$		-55 to +150				$^\circ\text{C}$

Note 1: Thermal resistance from junction to lead P.C.B. mounted on  $8.0 \times 8.0 \text{ mm}^2$  copper pad area.

REV:B

# SMD Efficient Fast Recovery Rectifiers

**COMCHIP**  
SMD Diodes Specialist

## Rating and Characteristic Curves (CEFM101-G Thru. CEFM105-G)

Fig.1 Reverse Characteristics

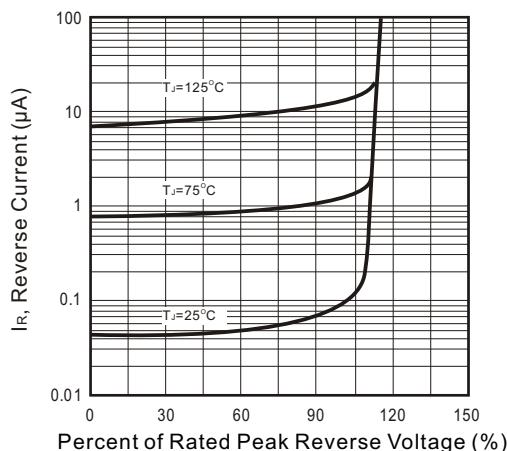


Fig.2 Forward Characteristics

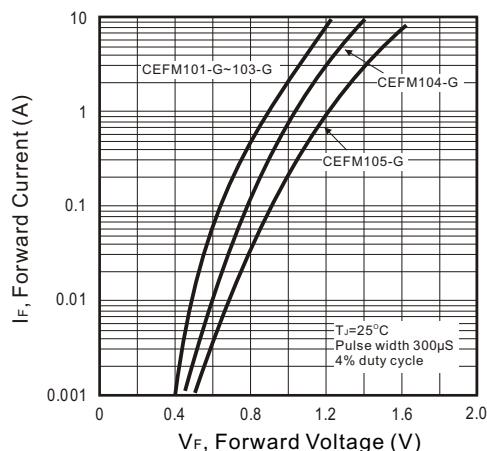


Fig.3 Junction Capacitance

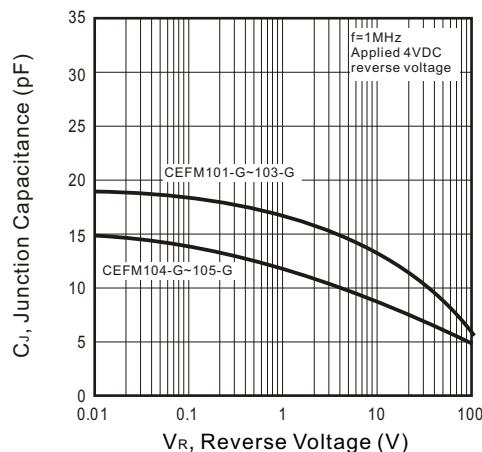


Fig.4 Current Derating Curve

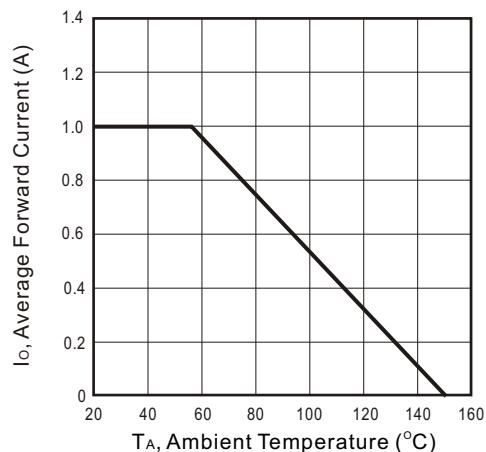


Fig.5 Non-repetitive Forward Surge Current

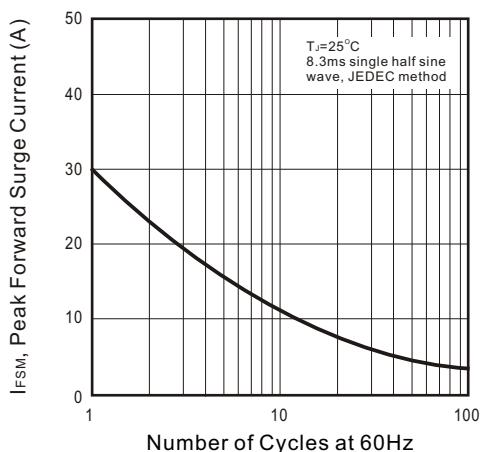


Fig.6 Test Circuit Diagram and Reverse Recovery Time Characteristics

